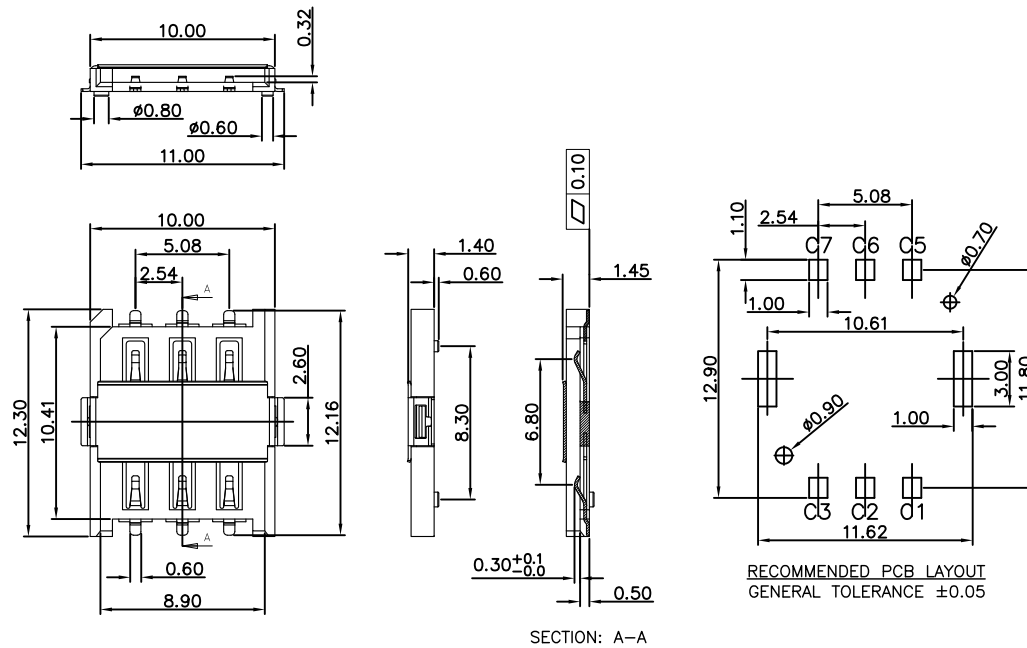
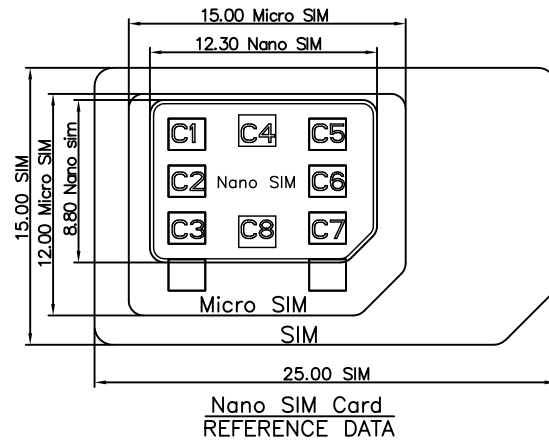
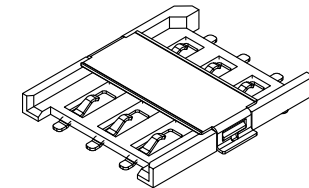
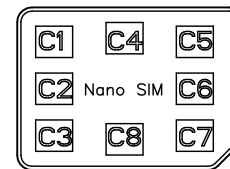




SECTION: A-A



C1 --> VCC
C2 --> RST
C3 --> CLK
C5 --> GND
C6 --> VPP
C7 --> I/O



Notes:

1.Material:

Housing: LCP 30%GF, UL94V-0, Black
Contact : Phosphor Bronze, T=0.15mm
Shell: SUS304-H, T=0.15mm

2.Plating:

Contact:

Contact Area: 3U" GOLD PLATED
Solder Area: G/F Gold
Underplating: Ni overall 50u" Min.

Shell:

Solder Area: G/F Gold
Underplating: Ni overall 50u"

3.Mechanical:

Life cycles: 5000.

4.Electrical:

Voltage Rating: 30V AC RMS
Current Rating: 0.5A AC RMS Max
Operating Temperature: -20°C to +80°C
Dielectric Withstanding Voltage: 100V AC (60Sec Min)
Insulation Resistance: 100MΩ Min
Contact Resistance: 30mΩ Max



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °		
X± 0.30	X*± 2 °		
.XX± 0.20	.XX*± 1 °		
		名 称(TITLE) Nano SIM CARD CONNECTOR 6PIN SMT TYPE (RoHS)	
单 位(UNIT)	料 号(PART NO.)	图 号(DWG NO.)	
mm	7SIMC-FA-0012	7SIMC-FA-0012-A	
审 核(APPROVAL)	核 对(CHECKED)	製 图(DRAWN)	比 例 SCALE 1:1 图 号 PROJ.
			张 数 SHEET 1/1 更 改 REV A